Thermoset SC-309 Thermally Conductive Silicone Encapsulant

Description

LORD Thermoset SC-309 thermally conductive silicone encapsulant is a two-component system designed to provide excellent thermal conductivity for electrical/ electronic encapsulating applications, while retaining desirable properties associated with silicones. Thermoset SC-309 encapsulant can be either room temperature cured or heat cured for maximum adhesion.

Features and Benefits

Low Stress – exhibits low shrinkage and stress on components as it cures.

Durable – composed of an addition-curing polydimethyl siloxane polymer that will not depolymerize when heated in confined spaces.

Low Viscosity – maintains low viscosity for ease of component encapsulation compared to other highly thermal conductive materials.

Environmentally Resistant – provides excellent thermal shock resistance.

UL Rated – provides excellent flame retardancy; UL 94 V-O certified.

Application

Mixing – Thoroughly stir each component prior to mixing together. Mix Thermoset SC-309 resin with Thermoset SC-309 hardener at a 1:1 ratio, by weight or volume. Automatic meter/mix/dispense equipment may be used for high volume production.

Unless a closed-chamber mechanical mixer is used, air will be introduced into the encapsulant system either during mixing or when catalyzing the mixture. Electrical properties of the silicone encapsulant are best when air bubbles and voids are minimized. Therefore, in extremely high voltage or other critical applications, vacuuming may be appropriate.

Applying – Apply silicone encapsulant using automatic meter/mix/dispense equipment.

Avoid applying Thermoset SC-309 encapsulant to surfaces that contain cure inhibiting ingredients, such as amines, sulfur or tin salts. If bonding surface is in question, apply a test patch of Thermoset SC-309 encapsulant to the surface and allow it to set for the normal cure time.

Typical Properties*

	SC-309 Resin	SC-309 Hardener	Mixed
Appearance	Gray Liquid	White Liquid	Light Gray Liquid
Viscosity, cps @ 25°C	3500	3500	3600
Specific Gravity	1.66	1.66	1.66
Gel Time, min @ 50°C	-	-	5-9
Working Life, min @ 25°C	_	_	30

*Data is typical and not to be used for specification purposes.



Typical Cured Properties**

Volume Resistivity, ohm-cm @ 25°C ASTM D 257	4.3 x 10 ¹³
Thermal Conductivity, W/mk Hot Disc Transient Method	1.0
Coefficient of Linear Thermal Expansion, ppm/°C ASTM C 864	190
Hardness Shore A, ASTM D 2240	45
Tensile Strength, MPa ASTM D 412	0.34
Moisture Absorption, % ASTM D 570-81	<0.5
Dielectric Strength, V/mil	600
Dielectric Constant @ 25°C 1 MHz, ASTM D 150	4.0
Dissipation Factor, % @ 25°C 1 MHz, ASTM D 150	0.004

**Cure schedule of 24 hours at 25°C plus 2 hours at 100°C.

Curing – Allow encapsulant to cure for 24 hours at room temperature (25°C), for 15 minutes at 100°C, or for 10 minutes at 120°C. This time-at-temperature profile refers to the time the material should be allowed to cure once it reaches the target temperature. Allowance should be made for oven ramp rates, parts with large thermal mass and other circumstances that may delay material actually reaching the target temperature.

Shelf Life/Storage

Shelf life of each component is six months from date of manufacture when stored at 25°C in original, unopened container. The material must be periodically rotated within its container to maintain maximum shelf life. Settling will occur if not mixed.

Thermoset SC-309 encapsulant evolves minute quantities of hydrogen gas. Do not repackage or store material in unvented containers. Adequately ventilate work area to prevent the accumulation of gas.

Cautionary Information

Before using this or any LORD product, refer to the Material Safety Data Sheet (MSDS) and label for safe use and handling instructions.

For industrial/commercial use only. Must be applied by trained personnel only. Not to be used in household applications. Not for consumer use.

Values stated in this technical data sheet represent typical values as not all tests are run on each lot of material produced. For formalized product specifications for specific product end uses, contact the Customer Support Center.

Information provided herein is based upon tests believed to be reliable. In as much as LORD Corporation has no control over the manner in which others may use this information, it does not guarantee the results to be obtained. In addition, LORD Corporation does not guarantee the performance of the product or the results obtained from the use of the product or this information where the product has been repackaged by any third party, including but not limited to any product end-user. Nor does the company make any express or implied warranty of merchantability or fitness for a particular purpose concerning the effects or results of such use.

"Ask Us How" is a trademark of LORD Corporation or one of its subsidiaries.

LORD provides valuable expertise in adhesives and coatings, vibration and motion control, and magnetically responsive technologies. Our people work in collaboration with our customers to help them increase the value of their products. Innovative and responsive in an ever-changing marketplace, we are focused on providing solutions for our customers worldwide ... Ask Us How.

LORD Corporation World Headquarters 111 Lord Drive Cary, NC 27511-7923 USA Customer Support Center (in United States & Canada) +1 877 ASK LORD (275 5673)

www.lord.com For a listing of our worldwide locations, visit LORD.com.

©2012 LORD Corporation OD DS3686 (Rev.3 10/12)

